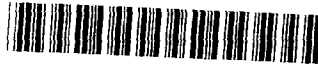


12/30/04

PATENTS ONLY

To the Hc
Patents ar
Please rec
document

01-14-2005



112955 U.S. PTO
11/026756



102920911

| | |
|--|---|
| <p>1. Name of party or parties conveying an interest:</p> <p>Yong Soo AHN</p> | <p>ty or parties receiving an interest:</p> <p>Name: DongbuAnam Semiconductor, Inc. a Korean corporation 891-10 Daechi-dong, Kangnam-ku, Seoul 135-523, Korea</p> |
| <p>3. Description of the interest conveyed:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement</p> <p>Execution Date: December 27, 2004</p> | <p>Other:</p> |
| <p>4. Application number(s) or patent number(s). Additional sheet attached? YES ___ NO <u>X</u></p> <p>A. Patent Application no.(s): Not Yet Assigned filed December 30, 2004</p> | <p>If the document is being filed together with a new application, the execution date of the application is:</p> <p>B. Patent no.(s):</p> |
| <p>5. Name and address of party to whom correspondence concerning this cover sheet should be mailed:</p> <p>Name: Mark G. Hanley Reg. No. 44,736 HANLEY, FLIGHT & ZIMMERMAN, LLC Street Address: 20 North Wacker Drive Suite 4220 City: Chicago State: Illinois Zip: 60606</p> | <p>6. Number of applications and/or patents identified on this cover sheet: 1</p> <p>7. Amount of fee enclosed or authorized to be charged: \$40.00</p> <p>8. Any additional required fee may be charged, or any overpayment credited to our deposit account: 50-2455</p> |

9. To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Date: December 30, 2004

Mark G. Hanley
Registration No. 44,736

Total number of pages including cover sheet, attachments, and document: 3

01/06/2005 JADD01 00000062 11026756
04 FC:8021 40.00 DP

A S S I G N M E N T

Serial No: _____

Filed: December 30, 2004Title: **METHOD FOR FORMING METALLIC INTERCONNECTS
IN SEMICONDUCTOR DEVICES**

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to DongbuAnam Semiconductor Inc., whose post-office address is 891-10 Daechi-dong, Gangnam-gu, Seoul 135-523 Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrants himself to be the owner of the interest herein assigned and to have the right to make this assignment and further warrants that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agrees upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of

